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Kind regards,

Team Nexperia

Product data sheet

#### 1. **General description**

The 74LVCH16541A is a 16-bit buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs (10En and 20En). A HIGH on nOEn causes the outputs to assume a high-impedance OFF-state.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs. These features allow the use of these devices in mixed 3.3 V and 5 V applications.

Bus hold on data inputs eliminates the need for external pull-up resistors to hold unused inputs.

#### 2. Features and benefits

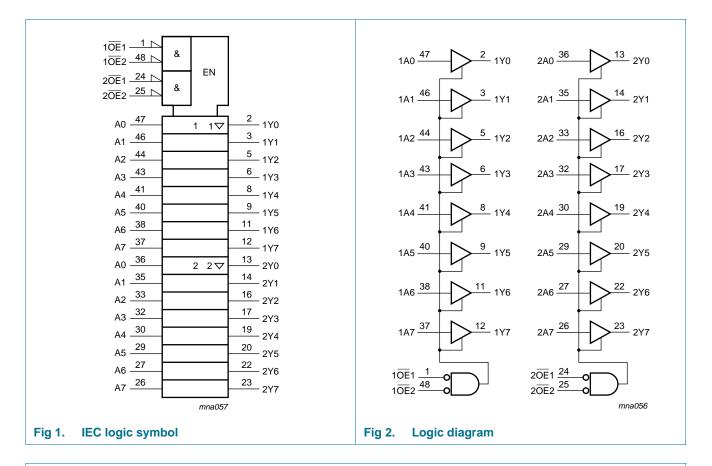
- 5 Volt tolerant inputs and outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low-power consumption
- MULTIBYTE flow-through standard pin-out architecture
- Low inductance multiple power and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- High-impedance outputs when V<sub>CC</sub> = 0 V
- All data inputs have bus hold
- Complies with JEDEC standard:
  - JESD8-7A (1.65 V to 1.95 V)
  - JESD8-5A (2.3 V to 2.7 V)
  - JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-B exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Specified from -40 °C to +85 °C and -40 °C to +125 °C.

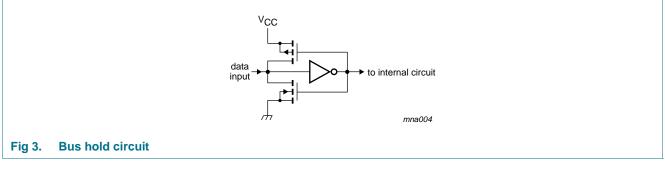


#### 3. Ordering information

Table 1. Ordering information										
Type number	Package	Package								
	Temperature range	Name	Description	Version						
74LVCH16541ADGG	–40 to +125 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1						
74LVCH16541ADL	–40 to +125 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1						

#### 4. Functional diagram



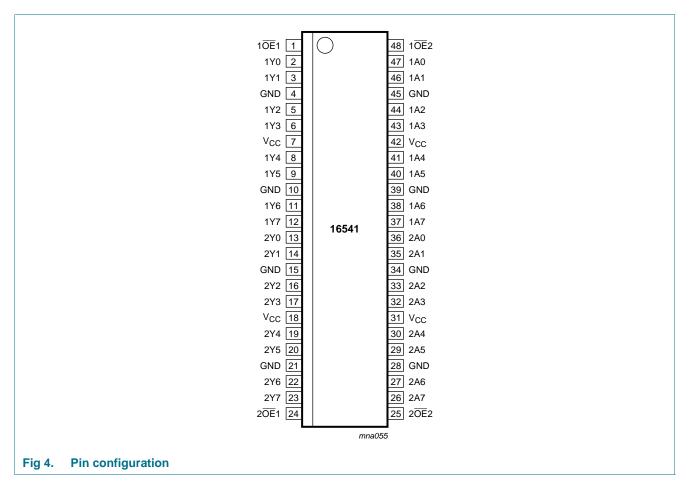


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#### 5. **Pinning information**

#### 5.1 Pinning



#### 5.2 Pin description

Table 2.	Pin description	
Name	Pin	Description
1 <del>OE</del> 1	1	output enable input (active LOW)
1 <mark>OE</mark> 2	48	output enable input (active LOW)
2 <mark>0E</mark> 1	24	output enable input (active LOW)
2 <mark>0E</mark> 2	25	output enable input (active LOW)
GND	4, 10, 15, 21, 28, 34, 39, 45	ground (0 V)
V <sub>CC</sub>	7, 18, 31, 42	positive supply voltage
1Y[0:7]	2, 3, 5, 6, 8, 9, 11, 12	data output
2Y[0:7]	13, 14, 16, 17, 19, 20, 22, 23	data output
1A[0:7]	47, 46, 44, 43, 41, 40, 38, 37	data input
2A[0:7]	36, 35, 33, 32, 30, 29, 27, 26	data input

#### 6. Functional description

#### Table 3. Function table<sup>[1]</sup>

Input nOE1	Output		
n <mark>OE</mark> 1	nOE2	nAn	nYn
L	L	L	L
L	L	Н	Н
Х	Н	Х	Z
Н	Х	Х	Z

[1] H = HIGH voltage level

L = LOW voltage level

X = don't care

Z = high-impedance OFF-state

### 7. Limiting values

#### Table 4.Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

			•			,
Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC</sub>	supply voltage			-0.5	+6.5	V
VI	input voltage		<u>[1]</u>	-0.5	+6.5	V
I <sub>IK</sub>	input clamping current	V <sub>1</sub> < 0		-50	-	mA
Ι <sub>ΟΚ</sub>	output clamping current	$V_{\rm O}$ > $V_{\rm CC}$ or $V_{\rm O}$ < 0		-	±50	mA
Vo	output voltage	output HIGH or LOW state	[2]	-0.5	V <sub>CC</sub> + 0.5	V
		output 3-state	[2]	-0.5	+6.5	V
l <sub>O</sub>	output current	$V_{O} = 0 V$ to $V_{CC}$		-	±50	mA
I <sub>CC</sub>	supply current			-	100	mA
I <sub>GND</sub>	ground current			-100	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C
P <sub>tot</sub>	total power dissipation	$T_{amb} = -40 \ ^{\circ}C \ to \ +125 \ ^{\circ}C$	[3]	-	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] Above 60 °C the value of  $\mathsf{P}_{tot}$  derates linearly with 5.5 mW/K.

16-bit buffer/line driver; 3-state

#### 8. Recommended operating conditions

Table 5.	Recommended operating operation	tions			
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		1.65	3.6	V
		functional	1.2	-	V
VI	input voltage		0	5.5	V
Vo	output voltage	output HIGH or LOW state	0	V <sub>CC</sub>	V
		output 3-state or $V_{CC} = 0 V$	0	5.5	V
T <sub>amb</sub>	ambient temperature	in free air	-40	+125	°C
Δt/ΔV	input transition rise and fall rate	$V_{CC}$ = 1.65 V to 2.7 V	0	20	ns/V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0	10	ns/V

#### 9. Static characteristics

#### Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +8	35 °C	–40 °C to	Unit	
			Min	Typ <mark>[1]</mark>	Max	Min	Max	
VIH	HIGH-level input	V <sub>CC</sub> = 1.2 V	1.08	-	-	1.08	-	V
	voltage	$V_{CC}$ = 1.65 V to 1.95 V	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	V
		$V_{CC}$ = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		$V_{CC}$ = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
VIL	LOW-level input	V <sub>CC</sub> = 1.2 V	-	-	0.12	-	0.12	V
	voltage	$V_{CC}$ = 1.65 V to 1.95 V	-	-	$0.35\times V_{CC}$	-	$0.35 \times V_{CC}$	V
		$V_{CC}$ = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		$V_{CC} = 2.7 \text{ V} \text{ to } 3.6 \text{ V}$	-	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level	$V_{I} = V_{IH} \text{ or } V_{IL}$						
output voltage	output voltage	$I_{O} = -100 \ \mu\text{A};$ $V_{CC} = 1.65 \ \text{V} \text{ to } 3.6 \ \text{V}$	$V_{CC}-0.2$	V <sub>CC</sub>	-	$V_{CC}-0.3$	-	V
		$I_{O} = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	-	-	1.05	-	V
		$I_{O} = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	-	-	1.65	-	V
		$I_{O}$ = -12 mA; $V_{CC}$ = 2.7 V	2.2	-	-	2.05	-	V
		$I_{O} = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	-	-	2.25	-	V
		$I_{O} = -24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.2	-	-	2.0	-	V
V <sub>OL</sub>	LOW-level	$V_{I} = V_{IH} \text{ or } V_{IL}$						
	output voltage	I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		$I_0 = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	-	0.45	-	0.65	V
		$I_{O} = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.6	-	0.8	V
		$I_0 = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	-	0.4	-	0.6	V
		$I_0 = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.55	-	0.8	V
I	input leakage current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = 5.5 V or GND <sup>[2]</sup>	-	±0.1	±5	-	±20	μΑ
4LVCH16541A		All information provided in t	his document is subjec	t to legal discla	aimers.	G	© NXP B.V. 2012. All rig	hts resen

16-bit buffer/line driver; 3-state

Symbol	Parameter	Conditions		-40	°C to +8	35 °C	-40	°C to +125 °C	Unit
			N	/lin	Typ[1]	Max	Min	Max	
loz	OFF-state output current <sup>[2]</sup>	$      V_{I} = V_{IH} \text{ or } V_{IL}; V_{CC} = 3.6 \text{ V};                                   $	-		±0.1	±5	-	±20	μA
OFF	power-off leakage supply	$V_{CC}$ = 0 V; V <sub>I</sub> or V <sub>O</sub> = 5.5 V	-		±0.1	±10	-	±20	μA
lcc	supply current	$V_{CC} = 3.6 \text{ V};$ $V_I = V_{CC} \text{ or GND}; I_O = 0 \text{ A}$	-		0.1	20	-	80	μA
∆l <sub>CC</sub>	additional supply current	per input pin; $V_{CC} = 1.65 V \text{ to } 3.6 V;$ $V_I = V_{CC} - 0.6 V; I_O = 0 A$	-		5	500	-	5000	μA
Cı	input capacitance	$V_{CC} = 0 V$ to 3.6 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-		5.0	-	-	-	pF
I <sub>BHL</sub>	bus hold LOW	$V_{CC} = 1.65; V_I = 0.58 V$		10	-	-	10	-	μA
	current [3][4]	$V_{CC} = 2.3; V_1 = 0.7 V$	3	30	-	-	25	-	μA
		$V_{CC} = 3.0; V_{I} = 0.8 V$	7	75	-	-	60	-	μA
I <sub>BHH</sub>	bus hold HIGH	$V_{CC} = 1.65; V_I = 1.07 V$	_	-10	-	-	-10	-	μA
	current [3][4]	$V_{CC} = 2.3; V_I = 1.7 V$	_	-30	-	-	-25	-	μA
		$V_{CC} = 3.0; V_{I} = 2.0 V$	_	-75	-	-	-60	-	μA
BHLO	bus hold LOW	V <sub>CC</sub> = 1.95 V	2	200	-	-	200	-	μA
	overdrive current [3][5]	V <sub>CC</sub> = 2.7 V	3	00	-	-	300	-	μA
		V <sub>CC</sub> = 3.6 V	5	00	-	-	500	-	μA
BHHO	bus hold HIGH	V <sub>CC</sub> = 1.95 V	-2	200	-	-	-200	) -	μA
	overdrive current [3][5]	$V_{CC} = 2.7 V$	-3	300	-	-	-300	) -	μA
		V <sub>CC</sub> = 3.6 V	-5	500	-	-	-500	) -	μA

#### Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

[1] All typical values are measured at  $V_{CC}$  = 3.3 V (unless stated otherwise) and  $T_{amb}$  = 25 °C.

[2] The bus hold circuit is switched off when V<sub>I</sub> > V<sub>CC</sub> allowing 5.5 V on the input pin.

[3] For data inputs only; control inputs do not have a bus hold circuit.

[4] The specified sustaining current at the data inputs holds the input below the specified V<sub>I</sub> level.

[5] The specified overdrive current at the data input forces the data input to the opposite logic input state.

#### **10.** Dynamic characteristics

#### Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see <u>Figure 7</u>.

Symbol	Parameter	Conditions		T <sub>amb</sub> =	–40 °C to	+85 °C	–40 °C to	+125 °C	Unit
				Min	Typ <mark>[1]</mark>	Max	Min	Max	
t <sub>pd</sub>	propagation	nAn to nYn; see Figure 5	[2]						
delay	delay	V <sub>CC</sub> = 1.2 V		-	10	-	-	-	ns
		$V_{CC}$ = 1.65 V to 1.95 V		1.8	4.7	10.4	1.8	12.0	ns
		$V_{CC}$ = 2.3 V to 2.7 V		1.5	2.6	5.2	1.5	6.0	ns
		$V_{CC} = 2.7 V$		1.0	2.5	5.0	1.0	6.5	ns
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$		1.0	2.2	4.2	1.0	5.5	ns
t <sub>en</sub>	enable time	n <mark>OE</mark> n to nYn; see <u>Figure 6</u>	[2]						
		V <sub>CC</sub> = 1.2 V		-	17	-	-	-	ns
		$V_{CC}$ = 1.65 V to 1.95 V		1.5	5.5	14.6	1.5	16.8	ns
		$V_{CC}$ = 2.3 V to 2.7 V		1.0	3.2	7.7	1.0	8.9	ns
		$V_{CC} = 2.7 V$		1.5	3.4	6.9	1.5	9.0	ns
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$		1.0	2.6	5.6	1.0	7.0	ns
t <sub>dis</sub>	disable time	n <mark>OE</mark> n to nYn; see <u>Figure 6</u>	[2]						
		V <sub>CC</sub> = 1.2 V		-	9.0	-	-	-	ns
		$V_{CC}$ = 1.65 V to 1.95 V		2.6	7.3	9.2	2.6	10.6	ns
		$V_{CC}$ = 2.3 V to 2.7 V		1.0	4.1	5.2	1.0	6.0	ns
		$V_{CC} = 2.7 V$		1.5	4.6	6.5	1.5	8.5	ns
		$V_{CC}$ = 3.0 V to 3.6 V		1.5	4.5	5.5	1.5	7.0	ns
t <sub>sk(o)</sub>	output skew time	$V_{CC}$ = 3.0 V to 3.6 V	<u>[3]</u>	-	-	1.0	-	1.5	ns
C <sub>PD</sub>	power	per input; $V_I = GND$ to $V_{CC}$	[4]						
	dissipation	$V_{CC}$ = 1.65 V to 1.95 V		-	8.5	-	-	-	pF
	capacitance	$V_{CC}$ = 2.3 V to 2.7 V		-	12.1	-	-	-	pF
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$		-	15.3	-	-	-	pF

[1] Typical values are measured at  $T_{amb}$  = 25 °C and  $V_{CC}$  = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

 $t_{en}$  is the same as  $t_{\text{PZL}}$  and  $t_{\text{PZH}}.$ 

 $t_{\text{dis}}$  is the same as  $t_{\text{PLZ}}$  and  $t_{\text{PHZ}}.$ 

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4]  $C_{PD}$  is used to determine the dynamic power dissipation (P<sub>D</sub> in  $\mu$ W).

 $\mathsf{P}_{\mathsf{D}} = \mathsf{C}_{\mathsf{P}\mathsf{D}} \times \mathsf{V}_{\mathsf{C}\mathsf{C}}^2 \times \mathsf{f}_i \times \mathsf{N} + \Sigma(\mathsf{C}_{\mathsf{L}} \times \mathsf{V}_{\mathsf{C}\mathsf{C}}^2 \times \mathsf{f}_o) \text{ where:}$ 

 $f_i$  = input frequency in MHz;  $f_o$  = output frequency in MHz

 $C_L$  = output load capacitance in pF

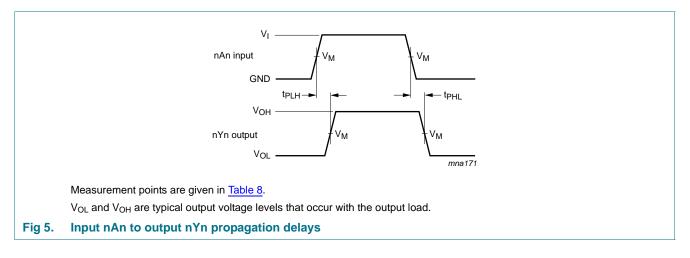
V<sub>CC</sub> = supply voltage in Volts

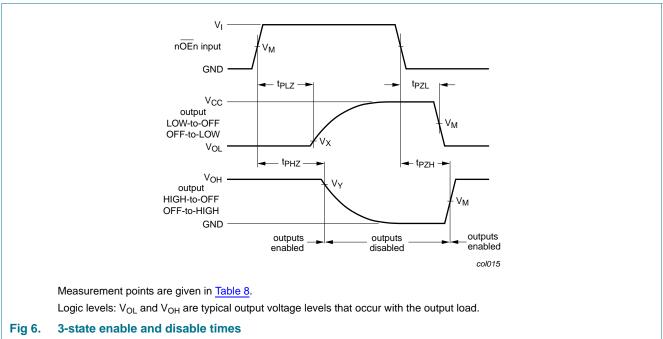
N = number of inputs switching

 $\Sigma(C_L \times V_{CC}{}^2 \times f_o)$  = sum of the outputs

16-bit buffer/line driver; 3-state

#### 11. Waveforms





#### Table 8.Measurement points

Supply voltage	V <sub>M</sub>	Input		
V <sub>CC</sub>		VI	V <sub>X</sub>	V <sub>Y</sub>
1.2 V	$0.5\times V_{CC}$	V <sub>CC</sub>	V <sub>OL</sub> + 0.15 V	V <sub>OH</sub> – 0.15 V
1.65 V to 1.95 V	$0.5\times V_{CC}$	V <sub>CC</sub>	V <sub>OL</sub> + 0.15 V	V <sub>OH</sub> – 0.15 V
2.3 V to 2.7 V	$0.5\times V_{CC}$	V <sub>CC</sub>	V <sub>OL</sub> + 0.15 V	V <sub>OH</sub> – 0.15 V
2.7 V	1.5 V	2.7 V	V <sub>OL</sub> + 0.3 V	V <sub>OH</sub> – 0.3 V
3.0 V to 3.6 V	1.5 V	2.7 V	V <sub>OL</sub> + 0.3 V	V <sub>OH</sub> – 0.3 V

#### **NXP Semiconductors**

### 74LVCH16541A

16-bit buffer/line driver; 3-state

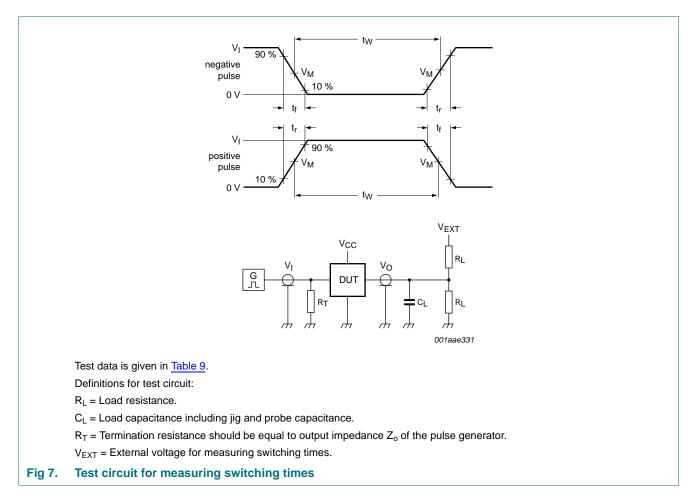
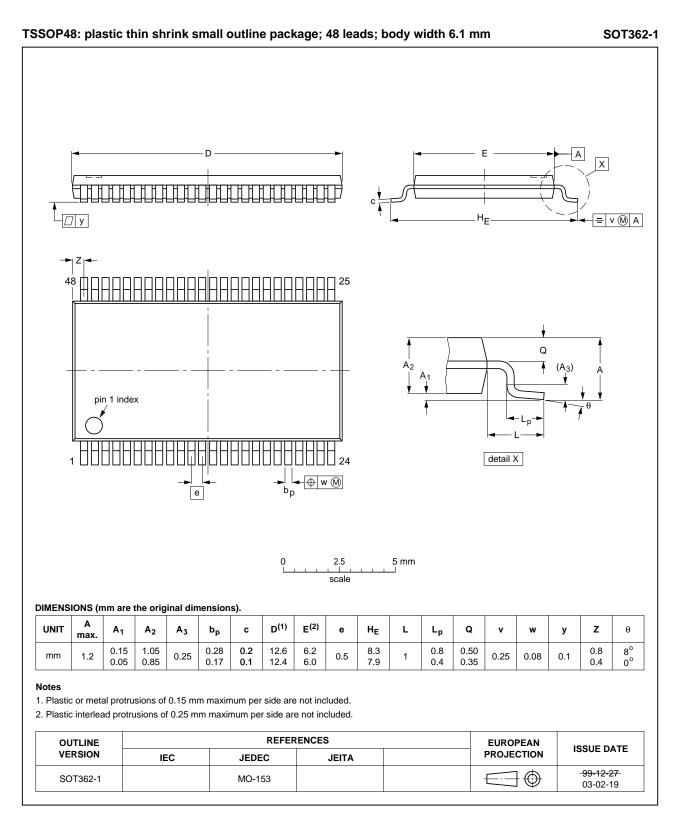


Table	<b>∋ 9</b> .	Test	data

Supply voltage	Input	ut		Load		V <sub>EXT</sub>		
	$V_I$ $t_r, t_f$ $C_L$ $R_L$ $t$		t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PLZ</sub> , t <sub>PZL</sub>	t <sub>PHZ</sub> , t <sub>PZH</sub>			
1.2 V	V <sub>CC</sub>	$\leq$ 2 ns	30 pF	1 kΩ	open	$2 \times V_{CC}$	GND	
1.65 V to 1.95 V	V <sub>CC</sub>	$\leq$ 2 ns	30 pF	1 kΩ	open	$2\times V_{CC}$	GND	
2.3 V to 2.7 V	V <sub>CC</sub>	$\leq$ 2 ns	30 pF	500 Ω	open	$2\times V_{CC}$	GND	
2.7 V	2.7 V	$\leq$ 2.5 ns	50 pF	500 Ω	open	$2\times V_{CC}$	GND	
3.0 V to 3.6 V	2.7 V	$\leq$ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND	

16-bit buffer/line driver; 3-state

#### 12. Package outline

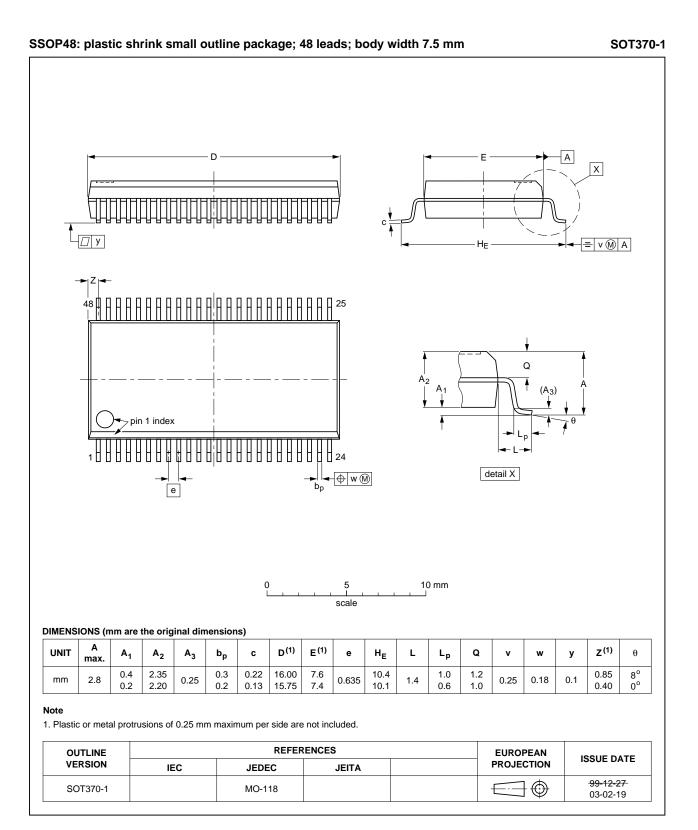


#### Fig 8. Package outline SOT362-1 (TSSOP48)

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74LVCH16541A

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#### Fig 9. Package outline SOT370-1 (SSOP48)

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16-bit buffer/line driver; 3-state

#### **13. Abbreviations**

Table 10.	Abbreviations
Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

### 14. Revision history

Table 11. Revision	history				
Document ID	Release date	Data sheet status	Change notice	Supersedes	
74LVCH16541A v.3	20120215	Product data sheet	-	74LVCH16541A v.2	
Modifications:	<ul> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> </ul>				
	<ul> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li><u>Table 4</u>, <u>Table 5</u>, <u>Table 6</u>, <u>Table 7</u>, and <u>Table 9</u>: values added for lower voltage ranges.</li> </ul>				
74LVCH16541A v.2	20040218	Product specification	-	74LVCH16541A v.1	
74LVCH16541A v.1	19980519	Product specification	-	-	

#### **15. Legal information**

#### **15.1 Data sheet status**

Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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